

LNPTTM THERMOCOMPTM COMPOUND ZF0089

ZF-1008 EP FR

DESCRIPTION

LNP THERMOCOMP ZF0089 compound is based on Polyphenylene Ether / Polystyrene (PPE/PS) blend containing 40% glass fiber. Added features of this grade include: Exceptional Processing, Flame Retardant.

GENERAL INFORMATION

Features	Flame Retardant, High Flow, High stiffness/Strength
Fillers	Glass Fiber
Polymer Types	Polyphenylene Ether + PS (PPE+PS)
Processing Techniques	Injection Molding

INDUSTRY

Building and Construction
Consumer
Electrical and Electronics
Industrial

SUB INDUSTRY

Building Component
Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Mobile Phone - Computer - Tablets
Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, brk, Type I, 5 mm/min	101	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	1	%	ASTM D638
Tensile Modulus, 50 mm/min	13020	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	131	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	11800	MPa	ASTM D790
Tensile Strain, break, 5 mm/min	0.8	%	ISO 527
Tensile Modulus, 1 mm/min	12280	MPa	ISO 527
Flexural Modulus, 2 mm/min	11940	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	332	J/m	ASTM D4812
Izod Impact, notched, 23°C	74	J/m	ASTM D256
Multiaxial Impact	3	J	ISO 6603
Instrumented Dart Impact Total Energy, 23°C	12	J	ASTM D3763
Izod Impact, unnotched 80°10°4 +23°C	19	kJ/m ²	ISO 180/1U
Izod Impact, notched 80°10°4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	110	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	103	°C	ASTM D648
CTE, -30°C to 30°C, flow	3.1E-05	1/°C	ASTM D696
CTE, -30°C to 30°C, xflow	5.4E-05	1/°C	ASTM D696

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CHEMISTRY THAT MATTERS™

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	112	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	105	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.52	-	ASTM D792
Density	1.52	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.07	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.2 – 0.5	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.5 – 0.8	%	ASTM D955
Density	1.51	g/cm ³	ISO 1183
Moisture Absorption (23°C / 50% RH)	0.09	%	ISO 62
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Melt Temperature	300 – 305	°C	
Front - Zone 3 Temperature	300 – 310	°C	
Middle - Zone 2 Temperature	290 – 300	°C	
Rear - Zone 1 Temperature	275 – 290	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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